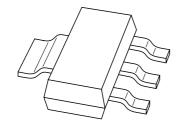
DISCRETE SEMICONDUCTORS

DATA SHEET



PZT4401NPN switching transistor

Product data sheet

1999 May 10



NPN switching transistor

PZT4401

FEATURES

- High current (max. 600 mA)
- · Low voltage.

APPLICATIONS

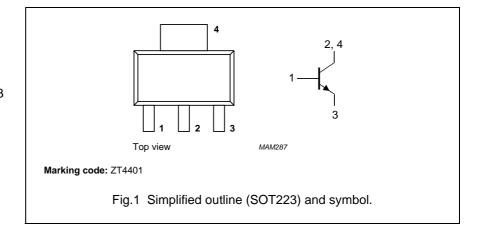
 Switching and linear amplification in industrial and consumer applications.

DESCRIPTION

NPN switching transistor in a SOT223 plastic package. PNP complement: PZT4403.

PINNING

| PIN | DESCRIPTION |
|------|-------------|
| 1 | base |
| 2, 4 | collector |
| 3 | emitter |



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | PARAMETER CONDITIONS | | MAX. | UNIT | |
|------------------|-------------------------------|----------------------------------|-----|------|------|--|
| V _{CBO} | collector-base voltage | open emitter | _ | 60 | V | |
| V_{CEO} | collector-emitter voltage | open base | _ | 40 | V | |
| V_{EBO} | emitter-base voltage | open collector | _ | 6 | V | |
| I _C | collector current (DC) | | _ | 600 | mA | |
| I _{CM} | peak collector current | | _ | 800 | mA | |
| I _{BM} | peak base current | | _ | 200 | mA | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C; note 1 | _ | 1150 | mW | |
| T _{stg} | storage temperature | | -65 | +150 | °C | |
| Tj | junction temperature | | _ | 150 | °C | |
| T _{amb} | operating ambient temperature | | -65 | +150 | °C | |

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

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THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------------|---|------------|-------|------|
| R _{th j-a} | thermal resistance from junction to ambient | note 1 | 109 | K/W |
| R _{th j-s} | thermal resistance from junction to soldering point | | 28 | K/W |

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

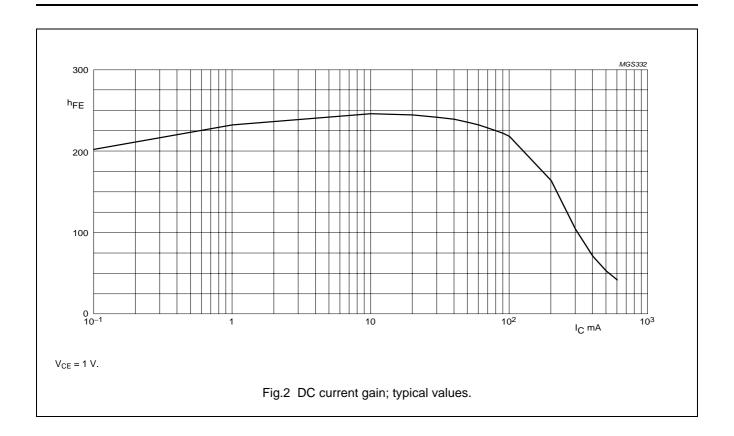
| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|--------------------|---------------------------------|---|------|------|------|
| I _{CBO} | collector cut-off current | I _E = 0; V _{CB} = 60 V | _ | 50 | nA |
| I _{EBO} | emitter cut-off current | I _C = 0; V _{EB} = 6 V | _ | 50 | nA |
| h _{FE} | DC current gain | V _{CE} = 1 V; see Fig.2 | | | |
| | | $I_{\rm C} = 0.1 \text{mA}$ | 20 | _ | |
| | | I _C = 1 mA | 40 | _ | |
| | | I _C = 10 mA | 80 | _ | |
| | | IC = 150 mA; note 1 | 100 | 300 | |
| | | V _{CE} = 2 V; I _C = 500 mA; note 1 | 40 | _ | |
| V _{CEsat} | collector-emitter saturation | I _C = 150 mA; I _B = 15 mA; note 1 | _ | 400 | mV |
| | voltage | I _C = 500 mA; I _B = 50 mA; note 1 | _ | 750 | mV |
| V _{BEsat} | base-emitter saturation voltage | I _C = 150 mA; I _B = 15 mA; note 1 | _ | 950 | mV |
| | | IC = 500 mA; IB = 50 mA; note 1 | _ | 1200 | mV |
| C _c | collector capacitance | I _E = i _e = 0; V _{CB} = 5 V; f = 1 MHz | _ | 8 | pF |
| C _e | emitter capacitance | $I_C = i_c = 0$; $V_{EB} = 500 \text{ mV}$; $f = 1 \text{ MHz}$ | _ | 30 | pF |
| f _T | transition frequency | I _C = 20 mA; V _{CE} = 10 V; f = 100 MHz | 250 | _ | MHz |
| Switching ti | mes (between 10% and 90% lev | els); see Fig.3 | | | |
| t _{on} | turn-on time | I _{Con} = 150 mA; I _{Bon} = 15 mA; | _ | 35 | ns |
| t _d | delay time | $I_{Boff} = -15 \text{ mA}; V_{BB} = -3.5 \text{ V};$ | _ | 15 | ns |
| t _r | rise time | V _{CC} = 29.5 V | _ | 20 | ns |
| t _{off} | turn-off time | | _ | 250 | ns |
| t _s | storage time | | _ | 200 | ns |
| t _f | fall time | | _ | 60 | ns |

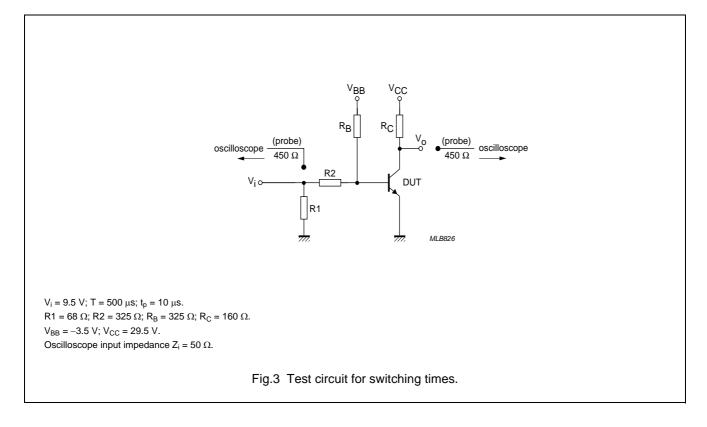
Note

1. Pulse test: $t_p \leq 300~\mu s;~\delta \leq 0.02.$

NPN switching transistor

PZT4401





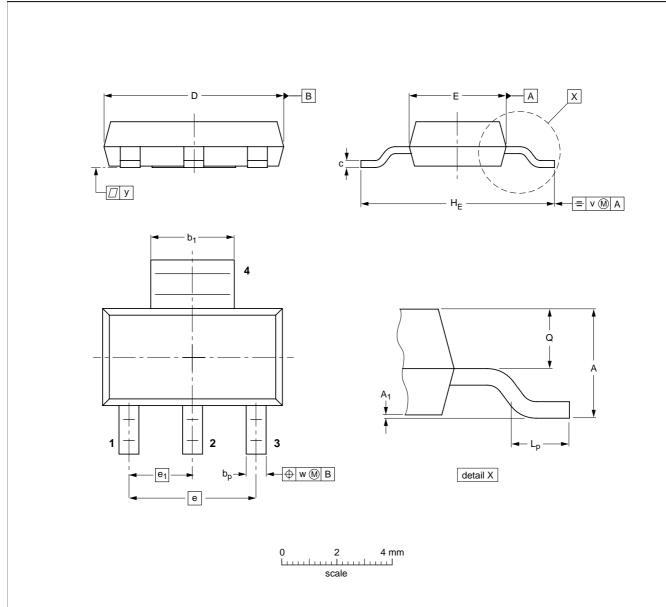
NPN switching transistor

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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

| UN | IIT | Α | A ₁ | bp | b ₁ | С | D | E | е | e ₁ | H _E | Lp | Q | v | w | у |
|----|-----|------------|----------------|--------------|----------------|--------------|------------|------------|-----|----------------|----------------|------------|--------------|-----|-----|-----|
| mı | m | 1.8 1.5 | 0.10 0.01 | 0.80 0.60 | 3.1 2.9 | 0.32 0.22 | 6.7 6.3 | 3.7 3.3 | 4.6 | 2.3 | 7.3 6.7 | 1.1 0.7 | 0.95 0.85 | 0.2 | 0.1 | 0.1 |

| OUTLINE | | REFER | EUROPEAN | ISSUE DATE | | | |
|---------|-----|-------|----------|------------|------------|---------------------------------|--|
| VERSION | IEC | JEDEC | EIAJ | | PROJECTION | ISSUE DATE | |
| SOT223 | | | SC-73 | | | 97-02-28 99-09-13 | |

NPN switching transistor

PZT4401

DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|-----------------------------------|----------------------------------|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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Customer notification

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Contact information

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